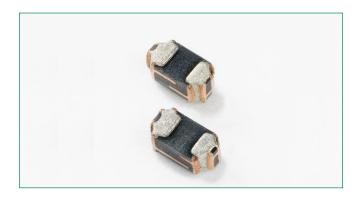
Surface Mount > 0402L Series

0402L Series





Description

The 0402L Series PTC provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.

Features

- RoHS compliant, lead-free and halogen free
- Fast response to fault currents
- Compact design saves board space
- Low resistance

- Low-profile
- Compatible with high temperature solders
- 0402 size- the smallest PPTC in the market compatible with high temperature solders

Agency Approvals

Agency	Agency File Number
c FL ° us	E183209
A	R50119118

Applications

- USB peripherals
- Disk drives
- CD-ROMs
- Plug and play protection for motherboards and peripherals
- PDAs / digital cameras
- Game console port protection
- Tablet and Notebook PCs
- E-readers

Additional Information



Datasheet



Resources



Electrical Characteristics

Part Number	l hold	I trin	V max	V I max			ım Time Irip	Resis	tance	Age Appro	
rait Nulliber	(A)	(A)	(Vdc)	(A)	(W)	Current (A)	Time (Sec.)	R _{min} (Ω)	R _{1max} (Ω)	c 71 2 us	A
0402L010SL	0.10	0.30	6	40	0.5	0.50	1.00	0.150	2.000	X	X
0402L020SL	0.20	0.50	6	40	0.5	1.00	1.00	0.100	1.250	X	X
0402L035SL	0.35	0.70	6	40	0.5	8.00	0.10	0.050	0.700	X	X
0402L050SL	0.50	1.00	6	40	0.5	8.00	0.10	0.040	0.400	X	X

_{lold} = Hold current: maximum current device will pass without tripping in 20°C still air.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

- · Users shall independently assess the suitability of these devices for each of their applications
- · Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses Circuits with inductance may generate a voltage (L di/dt) above the rated voltage of the PPTC device.

⁼Trip current: minimum current at which the device will trip in 20°C still air.

 $_{\max}^{\text{pp}}$ = Maximum voltage device can withstand without damage at rated current (I max) $_{\max}$ = Maximum fault current device can withstand without damage at rated voltage (V $_{\max}$)

⁼ Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

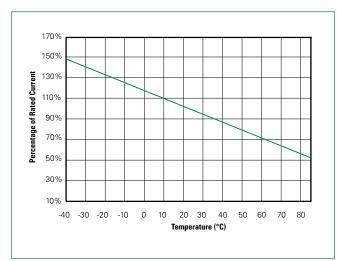
⁼ Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Surface Mount > 0402L Series

Temperature Rerating

	Ambient Operation Temperature								
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C
Part Number				F	lold Current (A	A)			
0402L010SL	0.14	0.13	0.11	0.10	0.09	0.08	0.07	0.06	0.05
0402L020SL	0.29	0.26	0.23	0.20	0.18	0.16	0.15	0.13	0.09
0402L035SL	0.50	0.45	0.40	0.35	0.31	0.28	0.26	0.22	0.16
0402L050SL	0.71	0.64	0.57	0.50	0.44	0.40	0.37	0.31	0.23

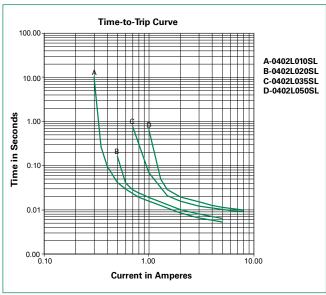
Temperature Rerating Curve



Note:

Typical Temperature rerating curve, refer to table for derating data

Average Time Current Curves

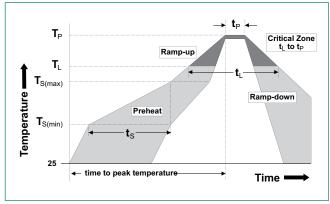


The average time current curves and Temperature Rerating curve performance is affected by a number or variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Surface Mount > 0402L Series

Soldering Parameters

Profile Feature	Pb-Free Assembly					
Average Ramp-Up	Average Ramp-Up Rate $(T_{S(max)} to T_p)$					
	150°C					
Pre Heat:	Temperature Max (T _{s(max)})	200°C				
	Time (Min to Max) (t _s)	60 – 180 secs				
Time Maintained	Temperature (T _L)	217°C				
Above:	Temperature (t _L)	60 - 150 seconds				
Peak / Classification	on Temperature (T _P)	260+0/-5 °C				
Time within 5°C of	f actual peak Temperature (t _p)	20 - 40 seconds				
Ramp-down Rate	6°C/second max					
Time 25°C to peak	8 minutes Max.					



- All temperature refer to topside of the package, measured on the package body surface
 If reflow temperature exceeds the recommended profile, devices may not meet the
- performance requirements $\ \, {\rm Recommended\ reflow\ methods:\ IR,\ vapor\ phase\ oven,\ hot\ air\ oven,\ N_2\ environment\ for}$
- Recommended maximum paste thickness is 0.25mm (0.010inch)
 Devices can be cleaned using standard industry methods and solvents
- Devices can be reworked using the standard industry practices

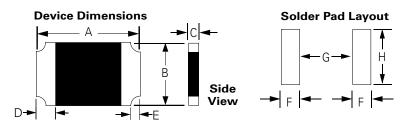
Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets ANSI/J-STD-002, Category C.

Environmental Specifications

Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883, Method 2007, Condition A No change
Moisture Sensitivity Level	Level 1, J-STD-020

Dimensions

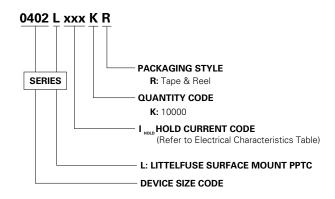


Device Top and Bottom Marking and Dimensions are Similar

		Device Dimension											Solder Pad																	
Part Number	Α .				E	3	С					D			E				F		F G		Н							
I dit ivuilibei	in	ch	m	m	in	ch	m	m	in	ch	m	ım	in	ch	m	m	inc	ch	mm		mm		mm		in ab		in ab		in ab	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	inch mm		inch	mm	inch	incn	mm			
0402L010SL	0.03	0.05	0.85	1.15	0.01	0.03	0.35	0.65	0.01	0.02	0.20	0.60	0.004	0.02	0.10	0.45	-	0.02	-	0.40	0.02	0.60	0.02	0.40	0.03	0.70				
0402L020SL	0.03	0.05	0.85	1.15	0.01	0.03	0.35	0.65	0.01	0.02	0.20	0.60	0.004	0.02	0.10	0.45	-	0.02	-	0.40	0.02	0.60	0.02	0.40	0.03	0.70				
0402L035SL	0.03	0.05	0.85	1.15	0.01	0.03	0.35	0.65	0.01	0.02	0.20	0.60	0.004	0.02	0.10	0.45	-	0.02	-	0.40	0.02	0.60	0.02	0.40	0.03	0.70				
0402L050SL	0.03	0.05	0.85	1.15	0.01	0.03	0.35	0.65	0.01	0.02	0.20	0.60	0.004	0.02	0.10	0.45	-	0.02	-	0.40	0.02	0.60	0.02	0.40	0.03	0.70				

Surface Mount > 0402L Series

Part Ordering Number System

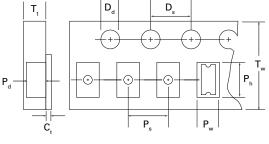


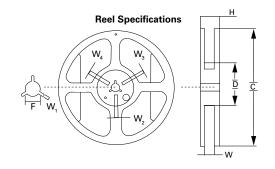
Packaging Quantity & Packaging **Part Number Ordering Number** I_{hold} (A) I bold Code **Packaging Option** 0402L010SL 0402L010SLKR 0.10 010 10,000 KR 0402L020SL 0402L020SLKR 020 Tape & Reel KR 0.20 10,000 0402L035SL 0402L035SLKR 035 10,000 KR 0.35 0402L050SL 0402L050SLKR 0.50 050 10,000 KR

Tape and Reel Specifications						
	TAPE SPECIFICATIONS: EIA- 481-1 (mm)					
	0402L010SL 0402L020SL 0402L035SL 0402L050SL					
C _t	0.05 ± 0.01					
\mathbf{D}_{d}	1.5 ± 0.1					
D _s	4.0± 0.1					
P _d	0.41± 0.1					
P _h	1.12± 0.1					
P _s	2.0 ± 0.1					
P _w	0.65 ± 0.03					
T,	0.61 ± 0.1					
T _w	8.0 ± 0.1					
Leader min.	390					
Trailer min.	160					

	REEL DIMENSIONS EIA-481-1 (mm)							
Н	12.0± 0.5							
W	9.0 ± 0.5							
D	Ø60 ± 0.5							
F	Ø13.0 ± 0.2							
С	Ø178 ± 1							
$W_{\scriptscriptstyle 1}$	2.2 ± 0.5							
$W_{_2}$	3.0± 0.5							
W ₃	4.0 ± 0.5							
W ₄	5.5 ± 0.5							
$W_{_4}$	5.5+0.5							

Tape and Reel Diagram





Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.